



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

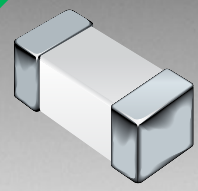
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\*RoHS COMPLIANT



**BOURNS®**

**Features**

- 0805 size
- Available in E12 Series
- High frequency
- Nickel barrier
- RoHS compliant\*



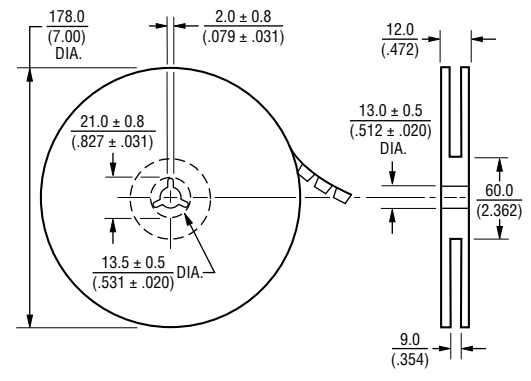
This series is currently available but not recommended for new designs.

**CE201210 Series - Multi-Layer Chip Inductors**

**Electrical Specifications**

Bourns Part No.	Inductance		Q Typ.	Test Frequency	SRF MHz	DCR	I rms
	nH	Tol. %	@100 MHz	L MHz	Min.	mohm Max.	mA Max.
CE201210-1N5D	1.5	± 0.3 nH	21	100	4000	100	300
CE201210-1N8D	1.8	± 0.3 nH	18	100	4000	100	300
CE201210-2N2D	2.2	± 0.3 nH	18	100	4000	100	300
CE201210-2N7D	2.8	± 0.3 nH	19	100	4000	100	300
CE201210-3N3J	3.3	± 5	16	100	4000	130	300
CE201210-3N9J	3.9	± 5	18	100	4000	150	300
CE201210-4N7J	4.7	± 5	18	100	3500	200	300
CE201210-5N6J	5.6	± 5	20	100	3200	230	300
CE201210-6N8J	6.8	± 5	20	100	2800	250	300
CE201210-8N2J	8.2	± 5	21	100	2400	280	300
CE201210-10NJ	10	± 5	20	100	2100	300	300
CE201210-12NJ	12	± 5	21	100	1900	350	300
CE201210-15NJ	15	± 5	22	100	1600	400	300
CE201210-18NJ	18	± 5	24	100	1500	450	300
CE201210-22NJ	22	± 5	23	100	1400	500	300
CE201210-27NJ	27	± 5	23	100	1300	550	300
CE201210-33NJ	33	± 5	24	100	1200	600	300
CE201210-39NJ	39	± 5	23	100	1000	650	300
CE201210-47NJ	47	± 5	23	100	900	700	300
CE201210-56NJ	56	± 5	23	100	800	750	300
CE201210-68NJ	68	± 5	25	100	700	800	300
CE201210-82NJ	82	± 5	24	100	600	900	300
CE201210-R10J	100	± 5	23	100	600	900	300
CE201210-R12J	120	± 5	22	50	500	950	300
CE201210-R15J	150	± 5	22	50	500	1000	300
CE201210-R18J	180	± 5	23	50	400	1100	300
CE201210-R22J	220	± 5	20	50	350	1200	300
CE201210-R27J	270	± 5	20	50	300	1300	300
CE201210-R33J	330	± 5	22	50	250	1400	300
CE201210-R39J	390	± 5	17	50	250	1300	300
CE201210-R47J	470	± 5	17	50	200	1500	300

**Packaging Specifications**



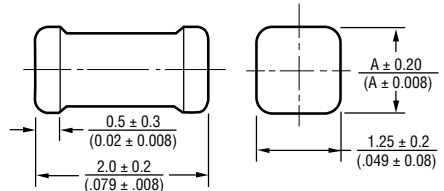
**General Specifications**

Temperature Rise .....30 °C max. at rated current  
 Operating Temperature .....-40 °C to +105 °C  
 Storage Temperature .....-40 °C to +105 °C  
 Reflow Soldering .. 230 °C, 50 sec. max.  
 Resistance to Soldering Heat ..... 260 °C, 10 sec.

**Materials**

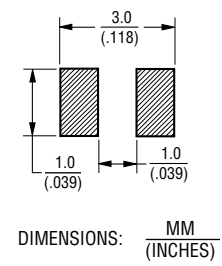
Base Material.....Ceramic  
 Terminal.....Ag/Ni/Sn  
 Packaging:  
 CE201210-1N5D through CE201210-82NJ.... 4,000 pcs. per reel  
 CE201210-R10J through CE201210-R27J.... 4,000 pcs. per reel  
 CE201210-R33J through CE201210-R47J.... 2,000 pcs. per reel

**Product Dimensions**



Model	Dimension A
CE201210-1N5D through CD201210-82NJ	0.83 (0.033)
CE201210-R10J through CE201210-R39J	1.00 (0.039)
CE201210-R47J	1.25 (0.050)

**Recommended Layout**



\*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011. Specifications are subject to change without notice. The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

## Applications

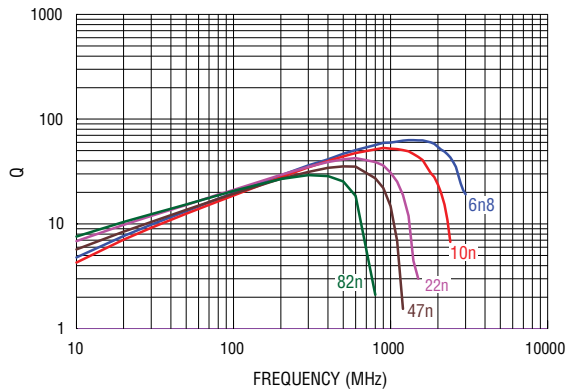
- Mobile phones
- Cellular phones
- CTV, VCR, HIC, FDD
- Automotive electronics

# CE201210 Series - Multi-Layer Chip Inductors

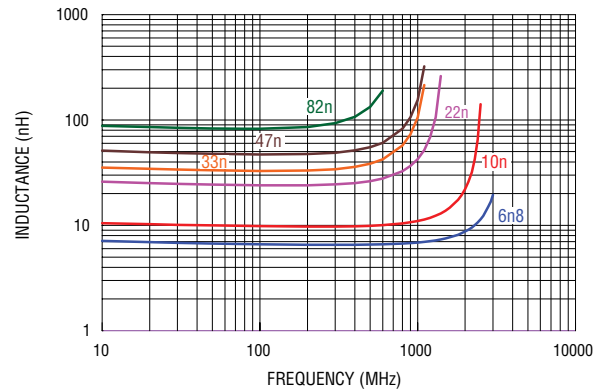
**BOURNS®**

## Electrical Specifications

**Q vs. Frequency Characteristics**



**Inductance vs. Frequency Characteristics**



REV. 04/17

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